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L Number	Hits	Search Text	DB	Time stamp
1	1	("5614311").PN.	USPAT	2002/03/25 14:02
2	154	(chip with tape) and permeability	USPAT;	2002/03/25 14:05
4			US-PGPUB;	
			EPO; JPO;	ł
			DERWENT;	
			IBM TDB	
3	6	(chip with tape) and (water adj	USPAT;	2002/03/25 14:50
		permeability)	US-PGPUB;	-00=,00,20 21.00
		*	EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	1	chip and (tape with g/m)	USPAT;	2002/03/25 14:11
	ł	*	US-PGPUB;	2002,00,20 11.11
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	15	chip and (g near m near h)	USPAT;	2002/03/25 14:48
			US-PGPUB;	_ = = = = = = = = = = = = = = = = = = =
			EPO; JPO;	
Ì			DERWENT;	
			IBM TDB	
6	218	(tape or substrate) with (water adj	USPAT;	2002/03/25 14:58
110		permeability)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
7	5	((tape or substrate) with (water adj	USPAT;	2002/03/25 14:53
		permeability)) and chip	US-PGPUB;	2002/03/23 14:33
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			DERWENT;	
			IBM TDB	}
8	18	((tape or substrate) with (water adj	USPAT;	2002/03/25 14:55
_		permeability)) and (chip or die)	US-PGPUB;	2002/03/23 14:33
		position of all all all all all all all all all al	EPO; JPO;	
			DERWENT;	
			IBM TDB	
9	1	(((tape or substrate) with (water adj	USPAT;	2002/03/25 14:56
		permeability)) and (chip or die)) and (g	US-PGPUB;	2002,00,20 11.00
		near m)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
10	9	((g/m) or (g near m)) same (water adj	USPAT;	2002/03/25 15:01
		permeability)	US-PGPUB;	2002,00,20 20.02
		[*	EPO; JPO;	
			DERWENT;	
			IBM TDB	
11	367	((g/m) or (g near m)) same permeab\$	USPAT;	2002/03/25 15:16
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			EPO; JPO;	
			DERWENT;	
			IBM TDB	
12	8	(((g/m) or (g near m)) same permeab\$) and	USPAT;	2002/03/25 15:14
	· ·	(chip or die) and (tape or substrate)	US-PGPUB;	2002/03/23 13:14
		(only of ale, and (cape of babselace)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
13	16	4971196.URPN.	USPAT	2002/03/25 15:12
14	0	20010028101.URPN.	USPAT	2002/03/25 15:12
15	2	"2001189400"	USPAT;	2002/03/25 15:14
		5007700400	US-PGPUB;	2002/03/23 13.13
			EPO; JPO;	
			DERWENT;	
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16	0	2001189400.URPN.	USPAT	2002/03/25 15:15
17	ő	2001189400.URPN.	USPAT	2002/03/25 15:15
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20	19		3 ((g/m) or (g near m)) near permeab\$	t.	2002/03/25 15:28
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22		1	adi napthalate)		
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29 0 11233567.URPN. USPAT USPAT USPAT 2002/03/25 15:41 USPAT USPAT; US-FGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-FGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-FGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-FGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-FGPU			= = = = = = = = = = = = = = = = = = =		2002/03/25 15:40
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31 2 "6012594"			012394	USPAT;	2002/03/25 15:43
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18M TOB 2					
SPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB uspat; and (polyethylene adj napthalate) SPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB uspat; and (polyethylene adj napthalate) SPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB uspat; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; D	21				
September Sept	31	2	"6012594"		2002/02/25 15 42
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33 3 "06021594" US-PGPUB; EPC; JPC; DERWENN; IBM TDB USPAT; US-PGPUB; EPC; JPC; DERWENN; IBM TDB USPAT	32	2	"06012594"		
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DERMENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB USPAT; US-PGPUB;					
33					
34 10 (chip or die or (device near semiconductor)) and (board or substrate) 15 2002/03/25 15:44 2002/03/25 15:44 2002/03/25 15:44 2002/03/25 15:44 2002/03/25 15:44 2002/03/25 2002/03/2	33	2	W0.0001504W		11/
10 (Chip or die or (device near semiconductor)) and (board or substrate) and (polyethylene adj napthalate) USPAT; USPGPUB; EPO; JPO; DERWENT; IEM TDB USPAT; USPAT; USPAT; USPGPUB; EPO; JPO; DERWENT; IEM TDB USPAT;		3	"06021594"		2002/03/25 15:44
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35 2 "11035715" EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT 2002/03/25 16:07		1	semiconductor)) and (board or substrate)		2002/03/25 15:53
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38 3 "04257444" DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; 15 4257444.URPN. 39 15 4257444.URPN. 40 15 4257444.URPN. USPAT 2002/03/25 16:02				EPO; JPO:	
38 3 "04257444" IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT 2002/03/25 16:07 15 4257444 URPN. USPAT 2002/03/25 16:02					
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41		0 "199118842"	USPAT;	2002/02/05 16 04
			US-PGPUB;	2002/03/25 16:04
			EPO; JPO;	
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42		3 "03148472"	IBM TDB	- 1
			USPAT;	2002/03/25 16:12
			US-PGPUB;	
			EPO; JPO; DERWENT;	
43		21.40.40	IBM TDB	
44	24	OICEN.	USPAT	2002/03/25 16:08
		20000383499"	USPAT;	2002/03/25 16:08
			US-PGPUB;	10:14
			EPO; JPO;	
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45	8	"0383499"	IBM TDB	
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46	0	W40303400#	IBM TDB	
		"40383499"	USPAT;	2002/03/25 16:14
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47	1	"04383499"	IBM TDB	
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			EPO; JPO;	
48			DERWENT; IBM TDB	
1 40	0	"2000383499"	USPAT;	2002/02/05 15
			US-PGPUB;	2002/03/25 16:17
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49	3	"04257444"	IBM TDB	
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			EPO; JPO;	
E O	1		DERWENT; IBM TDB	
50	2	"9952334 <i>"</i>	USPAT;	2000/02/05
			US-PGPUB;	2002/03/25 16:22
			EPO; JPO;	
			DERWENT;	
51	0	"1009200"	IBM TDB	
52	10	"1009200"	EPO	2002/03/25 16:21
		1009200	USPAT;	2002/03/25 16:21
			US-PGPUB;	
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r 0			DERWENT;	
53	10	"1009200"	IBM TDB	000040040-
			USPAT; US-PGPUB;	2002/03/25 16:31
			EPO; JPO;	
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			USPAT;	2002/03/25 16:32
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	<u> </u>		DERWENT; IBM TDB	
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56	0	"1998JP1532"	USPAT; 2002/03/25 16: US-PGPUB;
57 58	1 12	("5953592").PN. espanex	EPO; JPO; DERWENT; IBM TDB USPAT USPAT; US-PGPUB; EPO; JPO; 2002/03/25 16:
59 60 61	0 0 18	6291895.URPN. 6291895.URPN. ("4483067" "5063177" "5490324" "5602059" "5612576" "5683942" "5731231" "5737191" "5746390" "5753535" "5756379" "5834336" "5835355" "5874784" "5897337" "5950908" "5973404" "5976912").PN.	DERWENT; IBM TDB USPAT USPAT 2002/03/25 16: USPAT 2002/03/25 16: